

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Wei-Kuo Han</td><td>07/31/2008</td></tr><tr><td>Ming-Daw Chen</td><td>07/23/2008</td></tr></tbody></table>	Name	Execution Date	Wei-Kuo Han	07/31/2008	Ming-Daw Chen	07/23/2008	
Name	Execution Date						
Wei-Kuo Han	07/31/2008						
Ming-Daw Chen	07/23/2008						
RECEIVING PARTY DATA							
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City:	Hsinchu						
State/Country:	TAIWAN						
Postal Code:	31040						
PROPERTY NUMBERS Total: 1							
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12185827</td></tr></tbody></table>	Property Type	Number	Application Number:	12185827			
Property Type	Number						
Application Number:	12185827						
CORRESPONDENCE DATA							
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NAME OF SUBMITTER:	Belinda Lee						
Total Attachments: 2 source=26796assignment#page1.tif source=26796assignment#page2.tif							

12185827
CH \$40.00

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PATENT
REEL: 021399 FRAME: 0210

ASSIGNMENT

WHEREAS,

1. Han, Wei-Kuo

2. Chen, Ming-Daw

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **FLEXIBLE ELECTRET TRANSDUCER ASSEMBLY, SPEAKER, AND METHOD FOR FABRICATING FLEXIBLE ELECTRET TRANSDUCER ASSEMBLY**

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Han, Wei-Kuo

Date: July 31, 2008

Sole or First Joint Inventor: Han, Wei-Kuo

Signature: Chen, Ming-Daw

Date: 2008, 2, 23

Second Joint Inventor (if any): Chen, Ming-Daw